ABSTRACT

METHOD OF BONDING BUMPS TO LEADS OF TAB TAPE AND AN APPARATUS FOR ARRANGING BUMPS USED FOR THE SAME

A method of bonding bumps to leads of a TAB tape comprises the steps of preparing a substrate (5) which is provided with through-holes (13), each having a size which will not allow the bumps (4) to pass therethrough, at positions corresponding to bonding positions of the leads (3) of the TAB tape (12) where the bumps are to be bonded; provisionally arranging the bumps at positions of the through-holes at one side of the substrate by reducing a pressure in another side of the substrate opposite to said one side thereof to such the bumps in said through-holes; disposing the substrate on which the bumps are provisionally arranged and said TAB tape in such a positional relationship that said bumps face to the bonding positions of the leads of said TAB tape; and bonding the provisionally arranged bumps to the leads at the bonding positions and an apparatus for arranging bumps in a positional relationship corresponding to bonding positions of leads of a TAB tape.

This Sheet Has Been Replaced

